CMLD6001DO

SURFACE MOUNT SILICON DUAL, ISOLATED, OPPOSING ULTRA LOW LEAKAGE SWITCHING DIODE





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMLD6001DO type contains two (2) isolated opposing configuration, silicon switching diodes, manufactured by the epitaxial planar process, epoxy molded in an SOT-563 surface mount package. These devices are designed for switching applications requiring extremely low leakage.

MARKING CODE: C60

MAXIMUM RATINGS: (T _A =25°C) Continuous Reverse Voltage	SYMBOL V _R	75	UNITS V
Peak Repetitive Reverse Voltage	₹R V _{RRM}	100	V
Continuous Forward Current	I _F	250	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W

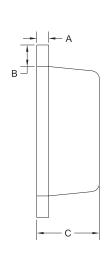
	CAL CHARACTERISTICS PER DIODE: TEST CONDITIONS V _R =75V	(T _A =25°C unles MIN	s otherwise noted) MAX 500	UNITS pA
BV_R	I _R =100μA	100		V
V_{F}	I _F =1.0mA		0.85	V
V_{F}	I _F =10mA		0.95	V
V_{F}	I _F =100mA		1.1	V
C_J	$V_R=0$, f=1.0MHz		2.0	pF
t _{rr}	$I_R = I_F = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω		3.0	μs

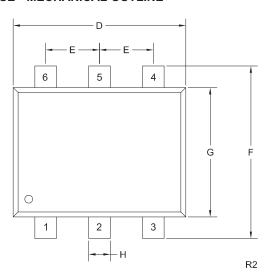
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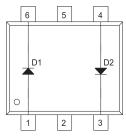


SOT-563 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.0027	0.007	0.07	0.18			
В	0.008		0.20				
С	0.017	0.024	0.45	0.60			
D	0.059	0.067	1.50	1.70			
E	0.020		0.50				
F	0.059	0.067	1.50	1.70			
G	0.043	0.051	1.10	1.30			
Н	0.006	0.012	0.15	0.30			
SOT-563 (REV: R2)							

LEAD CODE:

- 1) Anode D1
- 2) NC
- 3) Cathode D2
- 4) Anode D2
- 5) NC
- 6) Cathode D1

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R5 (15-June 2015)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors:

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